Product Data Sheet

Wafer Flux 5-SLC

Features

- Halogen-free
- Nitrogen reflow atmosphere

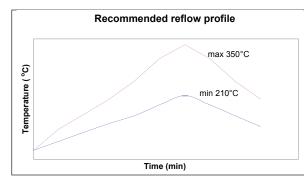
Introduction

Wafer Flux 5-SLC is a heat-stabilized rosin flux formulated for a wide range of metals and alloys. It has a wide process window, ranging from 125°C to 350°C. Electroplated Solder deposits form bright, spherical bumps when made using this flux. 5-SLC can be applied in dipping, spraying and spin-coating processes and can be used on Sn/Pb and Pb-Free alloys.

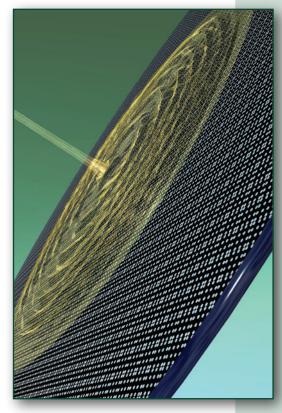
Typical Uncured Properties

Typical viscosity	37 Centistokes (cst)
Flash point	11°C
Flux type classification	ROLO
Visual appearance	Amber color liquid
Reflow atmosphere	<20ppm 0 ₂
Density	0.92g/cm ³

Reflow



This is the standard reflow profile for 5-SLC. The time to peak should be about 3 to 5 minutes. The peak temperature should be 20°C more than the melting point of the metal. Time above liquidus should be about 40 to 70sec.



Cleaning

Flux residue is non-corrosive, non-conductive and non-hydroscopic. Commercially available flux removers may be utilized for cleaning.

Packaging

Standard packagings for liquid fluxes are 1 US pint (425 grams) and 1 US gallon (3400 grams) containers.

Storage and Handling

The shelf life of 5-SLC is 1 year when stored at 0 to 30°C. Flux should be allowed to reach ambient temperature prior to use.

Material Safety Data Sheet

The MSDS for this product can be found online at http://www.indium.com/techlibrary/msds.php

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